

Bruce T. Murray—Publications in Thermal Management

1. M. I. Ibrahim, S. Bhopte, B. Sammakia, **B.T. Murray**, M. Iyengar, and R. Schmidt, Effect of Transient Boundary Conditions and Detailed Thermal Modeling of Data Center Rooms, IEEE Transactions on Components and Packaging Technologies, **2**, pp. 300-310, 2012.
2. Z. Song, **B.T. Murray** and B. Sammakia, Multi-Variate Prediction of Airflow and Temperature Distributions using Artificial Neural Networks, Proceedings of the ASME InterPACK Conference, IPACK2011-52167, Portland, Oregon, July 2011.
3. M. Ibrahim, F. Afram, B. Sammakia, K. Ghosh, **B.T. Murray**, M. Iyengar and R. Schmidt, Characterization of a Server Thermal Mass using Experimental Measurements, Proceedings of the ASME InterPACK Conference, IPACK2011-52165, Portland, Oregon, July 2011.
4. M. Ibrahim, B. Sammakia, S. Bhopte, **B.T. Murray**, M. Iyengar and R. Schmidt, Numerical Study on the Reduction of Recirculation using Sealed Cold Aisles and its Effects on the Efficiency of the Cooling Infrastructure, Proceedings of the ASME InterPACK Conference, IPACK2011-52166, Portland, Oregon, July 2011.
5. F. Zhou, P. Arunasalam, **B.T. Murray** and B. Sammakia, Modeling Heat Transport in Thermal Interface Materials Enhanced with MEMS based Microinterconnects, IEEE Transactions on Components and Packaging Technologies, **33**, pp. 16-24, 2010.
6. M. Ibrahim, S. Gondipalli, S. Bhopte, B. Sammakia, **B.T. Murray**, K. Ghosh, M. Iyengar and R. Schmidt, Numerical Modeling Approach to Dynamic Data Center Cooling, Proceedings of IEEE ITherm, Las Vegas, June 2010.
7. M. Ibrahim, S. Bhopte, B. Sammakia, **B.T. Murray**, M. Iyengar and R. Schmidt, Effect of Thermal Characteristics of Electronic Enclosures on Dynamic Data Center Performance, Proceedings of IMECE 2010 (ASME International Mechanical Engineering Congress and Exposition), Vancouver, British Columbia, paper IMECE2010-40914.
8. S. Gondipalli, B. Sammakia, S. Bhopte, R. Schmidt, M. Iyengar and B.T. Murray, Optimization of Cold Aisle Isolation Designs for a Data Center with Roofs and Doors using Slits, IPACK2009-89203, Proceedings of IPACK2009, San Francisco, California, July 2009.
9. F. Zhou, P. Arunasalam, **B.T. Murray** and B. Sammakia, Heat Transport in Thermal Interface Materials Enhanced with MEMS based Microinterconnects, ITherm Proceedings, IEEE, May 2008.
10. S. Bhopte, B. Sammakia and **B.T. Murray**, Geometric Modification to Simple Microchannel Design for Enhanced Mixing, Proceedings of the Inter-Society Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm), Orlando, Florida, IEEE, May 2008.

11. D.A. Davidson, G.L. Lehmann and **B.T. Murray**, Study of a Gel Thermal Interface Material with Micro-Sized Particles, Proceedings of the 10th ITherm Conference, San Diego, CA, pp. 497-504, 2006.
12. S. P. Watson, **B.T. Murray**, and B. G. Sammakia, Computational Parameter Study of Chip Scale Package Array Cooling, *IEEE Transactions on Components and Packaging Technologies*,**24**, pp. 184-190, 2001.
13. S. P. Watson, **B.T. Murray**, and B. G. Sammakia, Parametric Study of Chip Scale Package Array Cooling, Proceedings of the 2000 ASME-ITHERM Conference, pp.37-43, Las Vegas, NV, May 23-26, 2000.